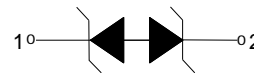


Features

- I Working voltages: 5V
- I Low Leakage Current
- I Low operating and clamping voltages
- I Lead Free/RoHS compliant
- I Solid-state silicon avalanche technology
- I Provides ESD protection to IEC61000-4-2(ESD): ±30kV (air discharge), ±30kV (contact discharge)



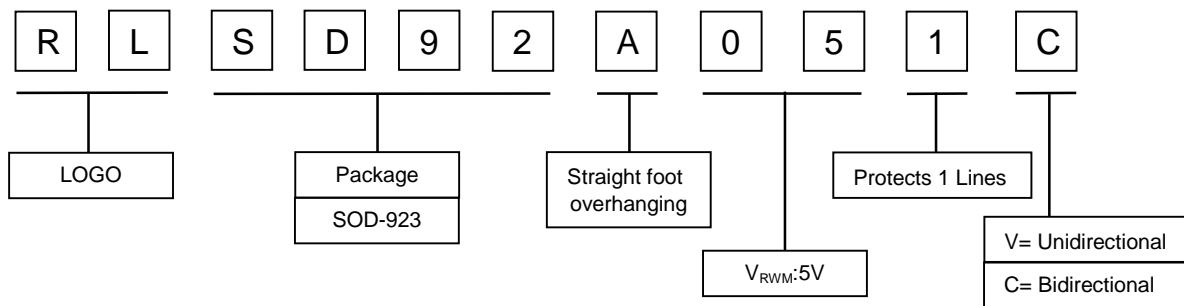
Electrical symbol



Applications

- I Cell Phone Handsets and Accessories
- I Microprocessor based equipment
- I Personal Digital Assistants (PDA's)
- I Notebooks, Desktops, and Servers
- I Portable Instrumentation
- I Pagers Peripherals

Part Number Code



Absolute Maximum Rating

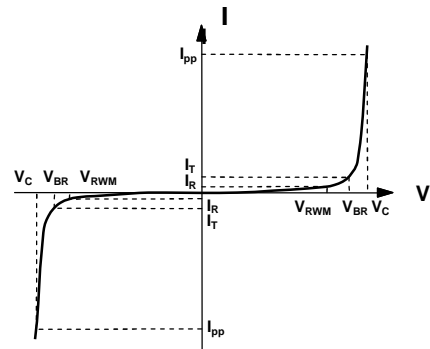
Rating	Symbol	Value	Units
ESD Voltage (Contact)	V_{ESD}	±30	kV
ESD Voltage (Air)	V_{ESD}	±30	kV
Lead Soldering Temperature	T_L	260 (10 sec.)	°C
Maximum junction temperature	T_J	150	°C
Storage Temperature	T_{STG}	-55 to 150	°C
Power Dissipation	P_D	150	mW

Electrical Characteristics (@ 25°C Unless Otherwise Specified)

Type Number	Reverse Stand-Off Voltage	Minimum Breakdown Voltage	Peak Pulse Voltage @8/20µS	V_C @8/20µS		Reverse Leakage @ V_{RWM}	Typical Capacitance
	V_{RWM}	V_{BR} @1mA	V_C @7A	(max.)	@ I_{PP}	I_R @ V_{RWM}	DC=0V C_J @ 1 MHz
	V	V	V	V	A	µA	pF
RLSD92A051C	5	6.0	9	9	7	1.0	13.5

Electrical Parameters (T=25°C)

Symbol	Parameter
I_{PP}	Maximum Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
V_{RWM}	Working Peak Reverse Voltage
I_R	Maximum Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current



Characteristic Curves

Fig 1. 8/20µs Pulse Waveform

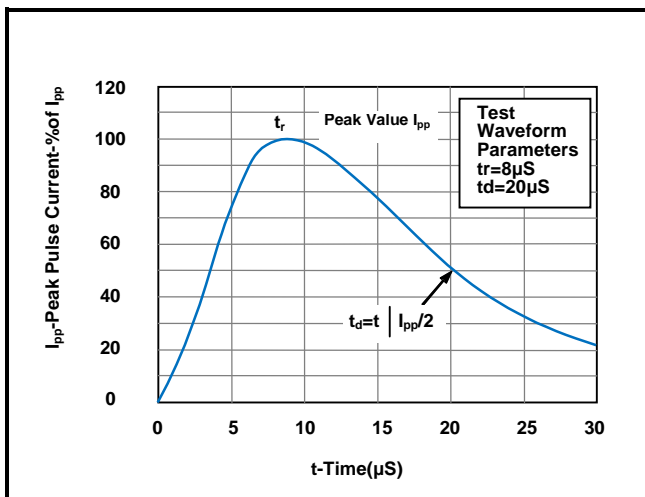


Fig 3. Power Derating Curve

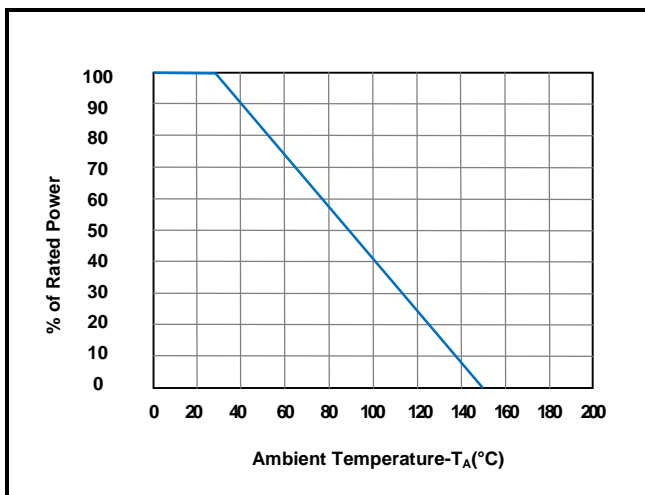


Fig2.ESD Pulse Waveform (according to IEC61000-4-2)

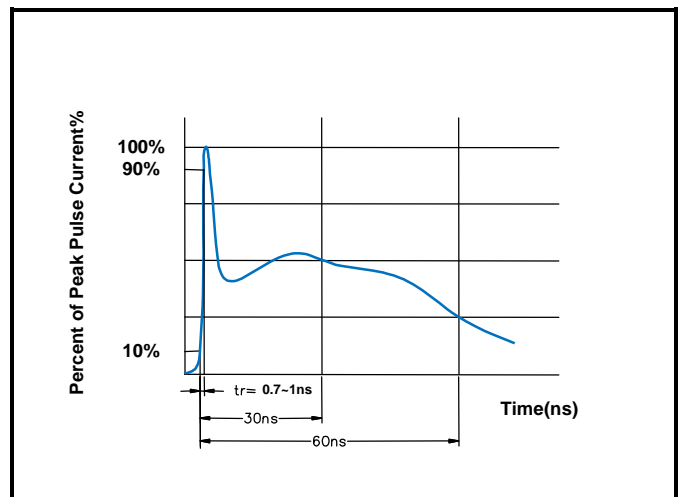
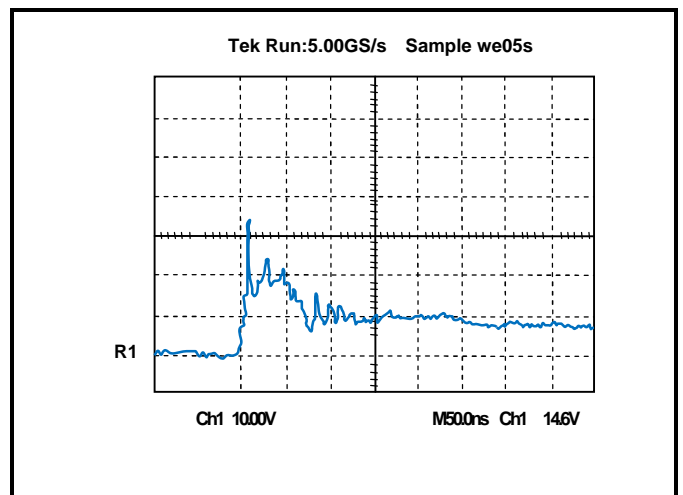
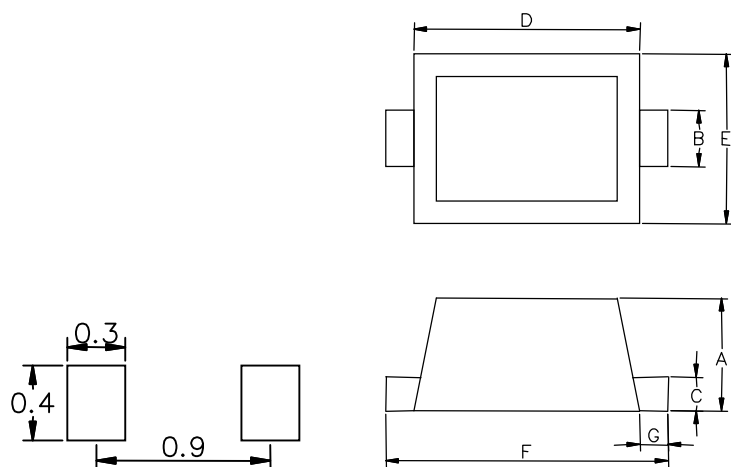


Figure 4.ESD Clamping(8KV Contact per IEC61000-4-2)



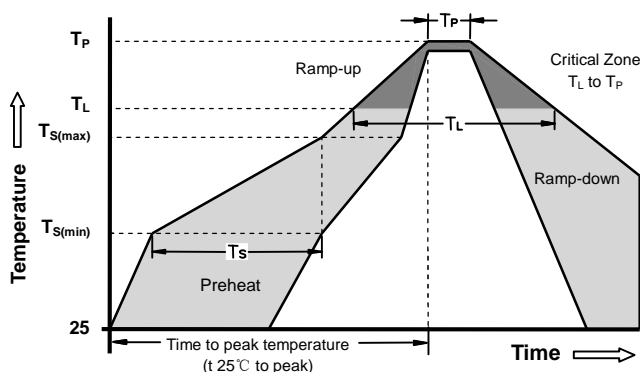
Dimensions & Recommended soldering footprint(mm)



DIM	Millimeters		Inches	
	Min	Max	Min	Max
A	0.34	0.40	0.013	0.016
B	0.15	0.25	0.006	0.010
C	0.07	0.17	0.003	0.007
D	0.75	0.85	0.030	0.033
E	0.55	0.65	0.022	0.026
F	0.95	1.05	0.037	0.041
G	0.05	0.15	0.002	0.006

Part Number	Component package	Quantity	Reel Size	Molding compound flammability rating	Lead Finish
RLSD92A051C	SOD-923	8000	7 inch	UL 94V-0	Matte tin (RoHS Compliant)

Soldering Parameters - Reflow Soldering (Surface Mount Devices)



Reflow Condition		Pb - Free assembly
Pre Heat	- Temperature Min ($T_{s(min)}$)	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (min to max) (t_s)	60 - 180 Seconds
Average ramp up rate (Liquids Temp T_L) to peak		3°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	- Temperature (T_L) (Liquids)	217°C
	- Time (min to max) (t_s)	60 - 150 Seconds
Peak Temperature (T_P)		260 +0/-5°C
Time within 5°C of actual peak Temperature (t_p)		20 - 40 Seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_P)		8 minutes Max
Do not exceed		280°C